T Number	Hits	Search Text	DB	Time stamp
L Number	926	257/685	USPAT;	2003/05/22 11:17
	720	2317 003	US-PGPUB;	
			EPO; JPO;	1
1 1			DERWENT	
	2074	257/686	USPAT;	2003/05/22 11:17
			US-PGPUB;	
1			EPO; JPO;	
	i		DERWENT	0003/05/33 13.34
-	4631	257/666	USPAT;	2003/05/22 13:24
			US-PGPUB;	
			EPO; JPO; DERWENT	
	2225	057 (600	USPAT;	2003/05/22 11:17
-	2235	257/690	US-PGPUB;	2003,03,22 11.1.
			EPO; JPO;	
			DERWENT	1
	2469	257/692	USPAT;	2003/05/22 11:17
-	2403	2317 032	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
_	1660	257/701	USPAT;	2003/05/22 11:17
	1000		US-PGPUB;	
İ		·	EPO; JPO;	•
			DERWENT	
-	4044	257/787	USPAT;	2003/05/22 11:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	13245	257/685 257/686 257/666 257/690 257/692	USPAT;	2003/05/22 11:18
		257/701 257/787	US-PGPUB;	
			EPO; JPO;	
			DERWENT	0000/05/00 10:10
-	3253	(257/685 257/686 257/666 257/690 257/692	USPAT;	2003/05/22 12:19
		257/701 257/787 ) and lead and (chip die	US-PGPUB;	
		IC (integrated near circuit)) and	EPO; JPO;	
		(encapsulant encapsulating encapsulate	DERWENT	
		mold)	HCDAM.	2003/05/22 11:22
-	965	((257/685 257/686 257/666 257/690 257/692	USPAT; US-PGPUB;	2003/03/22 11.22
		257/701 257/787 ) and lead and (chip die	EPO; JPO;	
		IC (integrated near circuit)) and (encapsulant encapsulating encapsulate	DERWENT	
		mold)) and ((I/O bond input/output) near	DEKNERT	
				i
	27	pad)   ((257/685 257/686 257/666 257/690 257/692	USPAT;	2003/05/22 13:22
-	21	257/701 257/787 ) and lead and (chip die	US-PGPUB;	
		IC (integrated near circuit)) and	EPO; JPO;	
		(encapsulant encapsulating encapsulate	DERWENT	
		mold)) and (lead near recess\$3)		
_	26	1	USPAT;	2003/05/22 13:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	9	(257/666 and (lead near recess\$3)) not	USPAT;	2003/05/22 13:22
		(((257/685 257/686 257/666 257/690 257/692	US-PGPUB;	
1		257/701 257/787 ) and lead and (chip die	EPO; JPO;	
		IC (integrated near circuit)) and	DERWENT	
1		(encapsulant encapsulating encapsulate		
		mold)) and (lead near recess\$3))	HCD200	2003/05/22 15:04
-	1450		USPAT;	2003/05/22 15:04
		encapsulating encapsulate mold)	US-PGPUB;	
			EPO; JPO; DERWENT	
		1057/566 and ship and (anamoulant	USPAT;	2003/05/22 15:04
-	1019	(257/666 and chip and (encapsulant	US-PGPUB;	2003,03/22 13.04
		encapsulating encapsulate mold)) not (((257/685 257/686 257/666 257/690 257/692	EPO; JPO;	
		(((257/685 257/686 257/686 257/690 257/692 257/701 257/787 ) and lead and (chip die	DERWENT	
		IC (integrated near circuit)) and		
	1	(encapsulant encapsulating encapsulate		
		mold)) and ((I/O bond input/output) near		
	1	pad))		
L	_l	Paci,		

£734					
[ <del>-</del>	781	((257/666 and chip and (encapsulant	USPAT;	2003/05/22 1	5:05
		encapsulating encapsulate mold)) not	US-PGPUB;		
		(((257/685 257/686 257/666 257/690 257/692	EPO; JPO;		
<u> </u>		257/701 257/787 ) and lead and (chip die	DERWENT		
		IC (integrated near circuit)) and			
		(encapsulant encapsulating encapsulate			
		mold)) and ((I/O bond input/output) near			
	204	pad))) and pad		0000/06/05	
_	294		USPAT;	2003/06/05 1	5:26
		near lead) and chip and ((I/O input/output) near pad)	US-PGPUB; EPO; JPO;		
		Imput/output/ near pad/	DERWENT		
_	1872	lead and chip and ((I/O input/output) near	USPAT;	2003/06/05 1	2.20
	10,2	pad)	US-PGPUB;	2003/06/03 1	.3:30
		pady	EPO; JPO;		
			DERWENT		
ļ <u>_</u>	668	(lead and chip and ((I/O input/output)	USPAT;	2003/06/05 1	5.28
		near pad)) and 257/\$6.ccls.	US-PGPUB;	2003,00,03	3.20
		, p, ,	EPO; JPO;		
	ĺ		DERWENT		
_	505	((lead and chip and ((I/O input/output)	USPAT;	2003/06/05 1	3:39
		near pad)) and 257/\$6.ccls.) not (((metal	US-PGPUB;		
		conductive conducting conductor) near	EPO; JPO;		
		lead) and chip and ((I/O input/output)	DERWENT		,
		near pad))			
-	294		USPAT;	2003/06/05 1	5:28
		near lead) and chip and ((I/O input/output	US-PGPUB;		
		bong) near pad)	EPO; JPO;		
	1016		DERWENT		
-	1346	, , , , , , , , , , , , , , , , , , ,	USPAT;	2003/06/05 1	5:28
		near lead) and chip and ((I/O input/output	US-PGPUB;		
		bond) near pad)	EPO; JPO;		
	1052	///	DERWENT	0000/05/05	
-	1052	, , , ,	USPAT;	2003/06/05 1	5:28
		near lead) and chip and ((I/O input/output bond) near pad)) not (((metal conductive	US-PGPUB;		
		conducting conductor) near lead) and chip	EPO; JPO; DERWENT		
		and ((I/O input/output) near pad))	DEKMENI		
_	516		USPAT;	2003/06/05 1	5.20
		near lead) and chip and ((I/O input/output	US-PGPUB;	2003/00/03 1	7.25
		bond) near pad)) not (((metal conductive	EPO; JPO;		Ì
		conducting conductor) near lead) and chip	DERWENT		
		and ((I/O input/output) near pad))) and			
		257/\$6.ccls.			
-	516	''''	USPAT;	2003/06/05 1	5:29
		conductor) near lead) and chip and ((I/O	US-PGPUB;		
		<pre>input/output bond) near pad)) not (((metal</pre>	EPO; JPO;		
		conductive conducting conductor) near	DERWENT		
		lead) and chip and ((I/O input/output)			
		near pad))) and 257/\$6.ccls.) not (((lead			İ
	İ	and chip and ((I/O input/output) near			
ĺ		pad)) and 257/\$6.ccls.) not ((metal			
		conductive conducting conductor) near lead) and chip and ((I/O input/output)			
		near pad)))			
		near paa, , ,		l .	Ī

Search History 6/13/03 4:32:31 PM Page 2 C:\APPS\east\workspaces\09816599.wsp